

Via Licensing Alliance Announces Call for Patents for First Semiconductor Patent Pool, Focused on Memory Technologies

SAN FRANCISCO, November 18, 2025 — Via Licensing Alliance has announced a formal call for patents for its first semiconductor patent pool, focused on memory technologies. This announcement follows Via's recent declaration that it is in the process of forming a series of patent pools within the semiconductor space.

The initial pool will address licensing for Dynamic Random Access Memory (DRAM), including several key categories of DRAM technology covered by the JEDEC standard:

- Double Data Rate (DDR3 and later)
- Low Power Double Data Rate (LPDDR4 and later)
- Graphics Double Data Rate (GDDR5 and later)
- High Bandwidth Memory (HBM)

DRAM technology has long been a key foundation of computing, serving as working memory that enables processors to operate efficiently. As the rapid scaling and adoption of AI technologies continue to drive exponential growth in compute demand, DRAM's fundamental value has significantly increased. DRAM forms the backbone of modern data processing that allow AI applications to develop and grow.

Via is creating a pool that will license DRAM, including at the datacenter level. While DRAM licensing has traditionally occurred at the manufacturing level, Via's new memory pool aims to extend licensing to the data center level to better capture the growing importance and value of DRAM in powering AI workloads.

"The importance of DRAM to today's AI technologies has fundamentally changed the value of patents in this space," said Willy Chang, Vice President of Programs at Via Licensing Alliance. "We look forward to working with our licensors to unlock the value that patented memory technologies bring to today's computing needs—most specifically, answering the massive demand for memory at the data center level generated by the continued growth of AI."

To be part of the pool formation process, Via invites companies with relevant standard essential DRAM patents to submit them, along with an applicable claim chart to the JEDEC standards identified above, to Via for consideration. Pool formation meetings are tentatively scheduled to begin in early 2026.

For more information or to express interest in contributing patents, please contact:

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About Via Licensing Alliance

Via Licensing Alliance is the collaborative licensing leader, dedicated to accelerating global technology adoption, fostering participation, and generating return on innovation with balanced licensing solutions for innovators and manufacturers of all sizes around the globe. Via has operated dozens of licensing



programs for a variety of technologies consisting of nearly 50,000 patents in over 130 countries with more than 500 patent holders and nearly 10,000 licensees. Via is an independently managed company owned by industry-leading participants with over 25 years of intellectual property licensing leadership. For more information about Via, please visit www.Via-LA.com.

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